



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD60R210CFD7		<b>Issued</b>		9. January 2019		
<b>MA#</b>		MA002182518						
<b>Package</b>		PG-TO252-3-342		<b>Weight*</b>		335.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.709	1.11	1.11	11069	11069
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		144	
	non noble metal	iron	7439-89-6	0.160	0.05		478	
	non noble metal	copper	7440-50-8	160.096	47.78	47.84	477765	478387
	non noble metal	aluminium	7429-90-5	0.965	0.29	0.29	2878	2878
wire	non noble metal	aluminium	7429-90-5	0.965	0.29	0.29	2878	2878
encapsulation	organic material	carbon black	1333-86-4	1.147	0.34		3424	
	plastics	epoxy resin	-	16.063	4.79		47936	
	inorganic material	silicondioxide	60676-86-0	126.209	37.66	42.79	376637	427997
leadfinish	non noble metal	tin	7440-31-5	3.740	1.12	1.12	11161	11161
plating	non noble metal	nickel	7440-02-0	0.523	0.16	0.16	1562	1562
solder	non noble metal	tin	7440-31-5	0.065	0.02		193	
	noble metal	silver	7440-22-4	0.081	0.02		241	
	non noble metal	lead	7439-92-1	3.086	0.92	0.96	9208	9642
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		17	
	non noble metal	iron	7439-89-6	0.019	0.01		57	
	non noble metal	copper	7440-50-8	19.177	5.72	5.73	57230	57304
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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